

**Semiconductor die products -
Part 8: EXPRESS model schema for data exchange
(IEC/TR 62258-8:2008)**

Produits à puce de semiconducteur -
Partie 8: Schéma du modèle EXPRESS
pour l'échange de données
(CEI/TR 62258-8:2008)

Halbleiter-Chip-Erzeugnisse -
Teil 8: EXPRESS-Modell-Schema
für den Datenaustausch
(IEC/TR 62258-8:2008)

This Technical Report was approved by CENELEC on 2008-06-01.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
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Foreword

The text of document 47/1927/DTR, future edition 1 of IEC/TR 62258-8, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as CLC/TR 62258-8 on 2008-06-01.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the Technical Report IEC/TR 62258-8:2008 was approved by CENELEC as a Technical Report without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050	Series	International Electrotechnical Vocabulary (IEV)	-	-
IEC 62258-1	- ¹⁾	Semiconductor die products - Part 1: Requirements for procurement and use	EN 62258-1	2005 ²⁾
IEC 62258-2	- ¹⁾	Semiconductor die products - Part 2: Exchange data formats	EN 62258-2	2005 ²⁾
IEC/TR 62258-4	- ¹⁾	Semiconductor die products - Part 4: Questionnaire for die users and suppliers	CLC/TR 62258-4	2007 ²⁾
IEC 62258-5	- ¹⁾	Semiconductor die products - Part 5: Requirements for information concerning electrical simulation	EN 62258-5	2006 ²⁾
IEC 62258-6	- ¹⁾	Semiconductor die products - Part 6: Requirements for information concerning thermal simulation	EN 62258-6	2006 ²⁾
ISO 10303-11	2004	Industrial automation systems and integration - Product data representation and exchange - Part 11: Description methods: The EXPRESS language reference manual	-	-
ISO 10303-21	2002	Industrial automation systems and integration - Product data representation and exchange - Part 21: Implementation methods: Clear text encoding of the exchange structure	-	-

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organisations that helped prepare this document included the ESPRIT ENCAST project, the Die Products Consortium, JEITA, JEDEC and ZVEI.

SEMICONDUCTOR DIE PRODUCTS –

Part 8: EXPRESS model schema for data exchange

1 Scope

This part of IEC 62258, which is a technical report, has been developed to facilitate the production, supply and use of semiconductor die products, including

- wafers,
- singulated bare die,
- die and wafers with attached connection structures,
- minimally or partially encapsulated die and wafers.

This Technical Report contains an EXPRESS model schema that describes the elements needed for data exchange and that will allow the implementation of the requirements of the IEC 62258-1, IEC 62258-5 and IEC 62258-6 standards, as well as providing an exchange structure that is complementary to those defined in IEC 62258-2. It is also complementary to and compatible with the questionnaire in IEC 62258-4.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary*

IEC 62258-1, *Semiconductor die products – Part 1: Requirements for procurement and use*

IEC 62258-2, *Semiconductor die products – Part 2: Exchange data formats*

IEC/TR 62258-4, *Semiconductor die products – Part 4: Questionnaire for die users and suppliers*

IEC 62258-5, *Semiconductor die products – Part 5: Requirements for information concerning electrical simulation*

IEC 62258-6, *Semiconductor die products – Part 6: Requirements for information concerning thermal simulation*

ISO 10303-11:2004, *Industrial automation systems and integration – Product data representation and exchange – Part 11: Description methods: The EXPRESS language reference manual*

ISO 10303-21:2002, *Industrial automation systems and integration – Product data representation and exchange – Part 21: Implementation methods: Clear text encoding of the exchange structure*